PC	PCN Number: 20110614001B PCN Date: 12/04/2013					12/04/2013					
Tit											
		PCN	l Ma	<u>nager</u>	Phone:	+1(214)480-6	037	Dept:	Qu	ality Services
Ch	ange Type:							<u> </u>			
\vdash	Assembly Site		Щ		bly Proces			<u>×</u>	Assembl	•	
H	Design Test Site				cal Specific g/Shipping		ıa	<u> </u>	Test Pro		pecification
Ħ	Wafer Bump Site				Bump Mat	•	9		Wafer B		Process
	Wafer Fab Site			Wafer	Fab Mater	ials			Wafer Fa		
	PCN Details										
De	scription of Change	e:									
	Revision B is to remove select devices in the Product Affected Section (with strikethrough) and highlighted in yellow. These devices were inadvertently added and not affected by this change.										
	alification of Cu bond OP, and SOP package	es	See	e table b	elow.		the QF	Ν, -	TQFP, QFP	, BG/	A, TSSOP,
					nd Wire (A		Additio		l Bond wir		
	Wire diameter (mils)		.8	, .96, 1.	15, 1.3 M	ıl Dıa.			.8, .96 Mi	l Dia.	
	ason for Change: To align with world to	och	nolo	av tren	de and us	o wiring	with an	har	nced		
	chanical and electric				us anu us	e wiring	with en	IIai	iceu		
	Maximize flexibility				mbly/Test	t product	ion site	es.			
	Cu is easier to obtai										
	ticipated impact or										
	s change is not expe the package.	cte	a to	nave ar	ny negativ	e impaci	t on the	e roi	rm, fit, fu	nctior	or reliability
	anges to product i	den	tifi	cation i	resulting	from th	is PCN	:			
No											
Pro	oduct Affected:										
Α[DS1299CPAG	В	Q30	423DBTF	?	PCM51	.41PWR		TI	PS516	40RSLT
Αſ	DS8555SPM	В	Q30	424DBTF	₹	PCM51	.42PW		TI	PS532	19RGTR
Α[DS8555SPMR	В	Q 33	200ZGVF	₹	PCM51	.42PWR		TI	PS611	87RTJR
Αſ	MC7812SRGCR	В	Q80	50DBTR-	·D1	PSN09	04005A3	3A12	ZCBR TI	PS657	35RSNR
ВС	Q20695DBTR	В	UF1	2840AIR	GER	PTPS65	735RSN	IR	TI	PS657	35RSNT
ВС	Q20Z451DBTR-R3	В	UF1	2840AIR	GET	PTPS65	735RSN	ΙΤ	TI	PS657	36RSNR
ВС	Q20Z459DBTR	С	D32	40B0ZRP	R	SN65L\	/PE5020	PRO	GER TI	PS658	624AZQZT
ВС	Q20Z656DBTR	С	DC7	36RHBR		SN74A	VC4T23	4ZSI	JR TI	PS658	640ZGUR
ВС	Q24707ARGRR	F	X00	2		SN804	5DBTR		TI	PS7A8	001DRBR
ВС	Q24707ARGRT	F	X00	8		SN9304	45A4ZQ	ZR	Ŧ	JSB13	<mark>10AZAY</mark>
ВС	Q24707RGRR	Н	IPAC	0934RG1	ΓR	TL16PC	C564BLV	IPZ	H	JSB13	10AZAYR
ВС	Q24707RGRT	Ν	/IAX	3243CPW	/R	TL16PC	C564BLV	IPZ	G4 TI	JSB92	60PVP
ВС	Q24725RGRR	٨	/IAX	3243CPW	/RE4	TLV320	AIC300	6IZC	QER TI	JSB92	61PVPR
ВС	Q24725RGRT	٨	/AX	3243CPW	/RG4	TLV320)AIC301	2IRF	IBR V	SP624	4BZRCR
ВС	Q24726RGRR	Р	CM3	3070IRHE	BR	TLV320	AIC37IZ	QEF	R V:	SP624	4BZSPR
ВС	Q24726RGRT	Р	CM	5100PW		TLV320	DAC33E	BNIZ	QCR V	SP682	6AZRCR
ВС	Q24735RGRR	Р	CM!	5100PWF	 }	TMDS3	51PAG		XI	0200	1IPNP

BQ24735RGRT	PCM5101PW	TMDS351PAGG4	XIO2211ZAJ
BQ24740RHDR	PCM5101PWR	TPS51211DSCR	XIO2211ZAY
BQ24740RHDRG4	PCM5102PW	TPS51211DSCT	XIO2213AZAY
BQ24747RHDT	PCM5102PWR	TPS51212DSCR	XIO2213BZAJ
BQ24760RSBR	PCM5121PW	TPS51212DSCT	XIO2213BZAJ
BQ29441DRBR	PCM5121PWR	TPS51220ARTVR	XIO2213BZAY
BQ30420DBTR	PCM5122PW	TPS51220ARTVR/2801	XIO2213ZAY
BQ30421DBTR	PCM5122PWR	TPS51220ARTVT	XIO2221ZAY
BQ30422DBTR	PCM5141PW	TPS51640RSLR	

Qualification Data: Approved 03/16/2010

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.								
Qual Vehicle 1: TMDS351PAG (MSL3-260C)								
Package Construction Details								
Assembly Site:	TI Taiwan	Mold Co	mpound:	4205442				
# Pins-Designator, Family:	64-PAG, TQFP	Mount Co	mpound:	4042504				
Leadframe (Finish, Base): NiPdAu, Cu			ond Wire:	0.96 Mil D	ia., Cu			
Qualification: Plan Test Results								
Reliability Test	Conditions		Pass / Fail					
Kellability Test			Lot 1	Lot2	Lot 3			
**High Temp. Storage Bake	170C (420 Hrs)		77/0	77/0	77/0			
**Biased HAST	130C/85%RH (96 Hrs)		77/0	77/0	77/0			
**Autoclave 121C	121C, 2 atm (96 Hrs)		77/0	77/0	77/0			
**T/C -65C/150C	-65C/+150C (500 Cyc)		77/0	77/0	77/0			
**T/C -55C/125C	-55C/+125C (1000 C	yc)	77/0	77/0	77/0			
Manufacturability	(per mfg. Site specifi	cation)	Pass	Pass	Pass			
**Thermal Shock	-65C/+150C (500 Cyc)		77/0	77/0	77/0			
Moisture Sensitivity (level 3 @ 260C +5/-0C) 12/0 12/0 12/0				12/0				
Notes: ** Tests require precenditioning sequence: MSL2 2600								

Notes: ** Tests require preconditioning sequence: MSL3-260C								
Qual Vehicle 2: TSB43AB23PDT (MSL3-260C)								
Package Construction Details								
Assembly Site:	TI-Taiwan	Mold Compo	und:	420	5442			
Pin Count, Package Family:	128-PDT, TQFP	Mount Compo	und:	404	2504			
Leadframe (Finish, Base):	NiPdAu, Cu	Bond \	Wire:	0.8	Mil Dia., Cı	ı		
Qualification: Plan Test Results:								
Reliability Test	Conditions		Sample Si		Size (PAS	S/FAIL)		
Reliability Test			Lot:	#1	Lot#2	Lot#3		
*High Temp. Storage Bake	170C (420 Hours)		77,	/0	77/0	77/0		
*Autoclave	121C, 2 atm, 96 Hou	urs	77,	/0	77/0	77/0		
T/C -65C/150C	-65C/+150°C (1000 C	ycles)	77/0		77/0	77/0		
T/C -55C/125C	-55C/+125C (1000,	Cycles)	77,	/0	77/0	77/0		
Manufacturability (Assembly)	(per mfg. Site specifica	ation)	Pas	SS	Pass	Pass		
Thermal Shock -65C/+150C (500, Cycles)			77,	/0	77/0	77/0		
Note* Tests require precondition	oning sequence: MSL3	-260C						

Qual Vehicle 3: TSB43DA42GHC (MSL3-220C)									
Package Construction Details									
Assembly Site:	TI-Taiwan	Mold Compo	und: 4203565						
Pin Count, Package Family:	196-GHC, UBGA	Mount Compo	und:	407	3505				
Solder Ball Composition: SnPb Bond Wire: 0.8 Mil Dia., Cu				Ţ					
Qualification: Plan Test Results									
Reliability Test	Conditions		Sample S		Size (PAS	S/FAIL)			
Reliability Test			Lot	#1	Lot#2	Lot#3			
**High Temp. Storage Bake	150C (1000 Hours)		77	//0	77/0	77/0			
**Unbiased HAST	130C/85%RH/33.3	psia (96 Hours)	77	//0	77/0	77/0			
**T/C -55C/+125C (1000 Cycles)			77	//0	77/0	77/0			
Manufacturability (Assembly)	(per mfg. Site specification)		Pa	SS	Pass	Pass			
Notes: **Tests require precon	ditioning sequence: MS	L3-220C							

Qualification Data: Approved 01/03/2011

Quannica	tion Data: App	novea or/o	3/2 () T T					
This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.									
Qual Vehicle 1: BUF16821BIPWP (MSL 2-260C)									
	Package Constru	ction Details							
Assembly Site:	TI Taiwan	Mold Comp	ound:	4205443					
# Pins-Designator, Family:	28-PWP, TSSOP	Mount Comp	ound:	4208458					
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:		Wire: 0.95 Mil Dia.,					
Qualification: Plan Test Results									
Reliability Test	Conditions	Conditions		Pass / Fail					
Reliability Test	Conditions			Lot2	Lot 3				
**High Temp. Storage Bake	170C (420 Hrs)		77/0	77/0	77/0				
**Biased HAST	130C/85%RH (9	6 Hrs)	77/0	77/0	77/0				
**Autoclave 121C	121C, 2 atm (96	Hrs)	77/0	77/0	77/0				
**T/C -65C/150C	-65C/+150C (50	0, 1000* Cyc)	77/0	77/0	77/0				
**T/C -55C/125C	00, 2000* Cyc)	77/0	77/0	77/0					
Manufacturability	(per mfg. Site sp	(per mfg. Site specification)		Pass	Pass				
**Thermal Shock	-65C/+150C (50	-65C/+150C (500, 1000* Cyc)		77/0	77/0				
1		·		1	1				

Qual Vehicle 2: TAS5086DBT (MSL 2-260C)							
Package Construction Details							
Assembly Site:	TI Taiwan	Mold Compound:	4206193				
# Pins-Designator, Family:	38-DBT, TSSOP	Mount Compound:	4042500				
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.96 Mil Dia., Cu				

Thermal Path Integrity (level 2 @ 260C +5/-0C)

Notes: **Tests require preconditioning sequence: MSL2-260C

12/0

12/0

12/0

Qualification:	✓ Test R	Results				
Reliability Test		Conditions			Pass / Fail	
•				Lot 1	Lot2	Lot 3
**High Temp Operating Life (A	(nalog	125C (1000 Hrs), Vddmax		77/0	77/0	77/0
**High Temp. Storage Bake		170C (420 Hrs)		77/0	77/0	77/0
**Biased HAST		130C/85%RI		77/0	77/0	77/0
**Autoclave 121C		121C, 2 atm		77/0	77/0	77/0
**T/C -65C/150C		-65C/+150C		77/0	77/0	77/0
**T/C -55C/125C		-55C/+125C		77/0	77/0	77/0
Manufacturability			e specification)	Pass	Pass	Pass
**Thermal Shock		-65C/+150C	(500 Cyc)	77/0	77/0	77/0
Moisture Sensitivity		(level 2 @ 2	50C +5/-0C)	12/0	12/0	12/0
Notes: **Tests require precond						
Qual Vehi			06IZQE (MSL 3	-260C)		
Assessable Cite		ge Construct			4205067	
Assembly Site:	TI Taiwa			mpound:	4205867	
# Pins-Designator, Family:	80-ZQE,	BGA		mpound:	4111062	
Solder Ball Composition:	SnAgCu		В	ond Wire:	0.8 Mil Dia	., Cu
Qualification: Plan		esults		1		
Reliability Test Conditions				Pass / Fail		
,				Lot 1	Lot2	Lot 3
**High Temp. Storage Bake	150C (1000 Hrs)			77/0	77/0	77/0
**Autoclave 121C		atm (96 Hrs)		77/0	77/0	77/0
**Unbiased HAST		5%RH (96 Hrs		77/0	77/0	77/0
**T/C -55C/125C		125C (1000 C		77/0	77/0	77/0
Manufacturability		g. Site specifi		Pass	Pass	Pass
Moisture Sensitivity		@ 260C +5/-		12/0	12/0	12/0
Notes: **Tests require precond						
Qual '			PAG (MSL 3-26	0C)		
		ge Construct			1	
Assembly Site:	TI Taiwa	n	Mold Co	mpound:	4205442	
# Pins-Designator, Family:	64-PAG,	TQFP	Mount Co	mpound:	4042504	
Leadframe (Finish, Base):	NiPdAu,	Cu	В	ond Wire:	0.95 Mil Di	ia., Cu
Qualification: Plan	🛚 Test R	esults				
Reliability Test	Conditio	ns			Pass / Fail	
,				Lot 1	Lot2	Lot 3
**High Temp. Storage Bake	•	000 Hrs)		77/0	77/0	77/0
**Biased HAST	130C/85%RH (96 Hrs)			77/0	77/0	77/0
**Autoclave 121C	121C, 2 atm (96 Hrs)			77/0	77/0	77/0
**T/C -55C/125C	-55C/+125C (1000 Cyc)			77/0	77/0	77/0
**T/C -65C/150C		50°C (500 Cycl		77/0	77/0	77/0
Manufacturability		g. Site specific		Pass	Pass	Pass
Moisture Sensitivity				12/0	12/0	12/0
Notes: **Tests require precond	ditioning	sequence: MS	SL3-260C			

Qual Vehicle 5: VSP6822AZRC (MSL 3-260C)								
Package Construction Details								
Assembly Site:	TI Taiwan	Mold Co	mpound:	4205867				
# Pins-Designator, Family:	98-ZRC, Jr BGA	Mount Co	mpound:	4111062				
Solder Ball Composition:	SnAgCu	Во	ond Wire:	0.8 Mil Dia	a., Cu			
Qualification: Plan	Qualification: Plan Test Results							
Reliability Test	Conditions			Pass / Fail	Fail			
Reliability Test			Lot 1	Lot2	Lot 3			
**High Temp. Storage Bake	150C (1000 Hrs)		77/0	77/0	77/0			
**Autoclave 121C	121C, 2 atm (96 Hrs)		77/0	77/0	77/0			
**Unbiased HAST	130C/85%RH (96 Hrs	5)	77/0	77/0	77/0			
**T/C -55C/125C	-55C/+125C (1000 C	yc)	77/0	77/0	77/0			
Manufacturability	(per mfg. Site specific	per mfg. Site specification)		Pass	Pass			
Moisture Sensitivity	(level 3 @ 260C +5/-0C)		12/0	12/0	12/0			
Notes: **Tests require precond	ditioning sequence: MS	SL3-260C						

Qual Vehicle 6: VSP6825AZRC (MSL 3-260C)								
Package Construction Details								
Assembly Site:	TI Taiwan	Mold Co	mpound:	4205867				
# Pins-Designator, Family:	103-ZRC, BGA	Mount Compound:		4111062				
Solder Ball Composition:	SnAgCu	Bond Wire:		0.8 Mil Dia., Cu				
Qualification: Plan	▼ Test Results							
Reliability Test	Conditions			Pass / Fail				
Reliability Test	Conditions		Lot 1	Lot2	Lot 3			
**Biased HAST 130C/85%RH (96 Hrs) 77/0			77/0	77/0				
Notes: **Test requires precond	ditioning sequence: MS	SL3-260C						

Qualification Data: Approved 07/07/2011

Qualification Data: Approved 07/07/2011								
This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.								
Qual Vehicle 1: ADS1230IPW (MSL2-260C)								
Package Construction Details								
Assembly Site:	TAI	Mold Compou	und:	420	6193			
Pin Count, Package Family:	16-PW, TSSOP	Mount Compound: 4042500						
Leadframe (Finish, Base):	NiPdAu, Cu	Bond Wire: 0.96 Mil Dia., C			. Cu			
Qualification: Plan	☐ Test Results							
Reliability Test	Conditions		San	nple S	Size (PAS	S/FAIL)		
Reliability Test	Conditions	Conditions		#1	Lot#2	Lot#3		
**High Temp. Storage Bake	150C (500, 1000 Ho	ours)	77	/0	77/0	77/0		
**Autoclave 121C	121C, 2 atm (96 Ho	urs)	77	/0	77/0	77/0		
**T/C -65C/150C	-65C/+150°C (500 Cy	-65C/+150°C (500 Cycles)		/0	77/0	77/0		
Manufacturability (Assembly) (per mfg. Site specification) Pass Pass Pass					Pass			
Notes: **Tests require preconditioning sequence: MSL2-260C								

Qual Vehicle 2: BQ24703RHD (MSL2-260C)							
Package Construction Details							
Assembly Site:	MLA	Mold Compound: 4208625					
# Pins-Designator, Family:	28-RHD, VQFN	Mount Co	Mount Compound: 4			4205846	
Leadframe (Finish, Base):	NiPdAu, Cu	Во	nd Wire:	0.9	96 Mil Dia.,	Cu	
Qualification: Plan Test Results							
Reliability Test	Conditions	Conditions			Pass / Fail		
,					Lot2	Lot 3	
**High Temp. Storage Bake	150C (420 Hrs)	_	77/0		77/0	77/0	
**Autoclave 121C	121C, 2 atm (96 Hrs		77/0		77/0	77/0	
**T/C -65C/150C	-65C/+150C (500, 1		77/0		77/0	77/0	
Manufacturability	(per mfg. Site specif		Pass		Pass	Pass	
Notes: **Tests require precon	ditioning sequence: N	4SL2-260C					
Qual V	ehicle 3: BUF07704	AIPWP (MSL2	-260C)				
	Package Constru	ction Details					
Assembly Site:	MLA	Mold	Compoun	d:	4205443		
# Pins-Designator, Family:	20-PWP, HTSSOP	Mount	Compoun	d: 4042504			
Leadframe (Finish, Base):	NiPdAu, Cu	, Cu Bond Wire:			0.96 Mil Dia., Cu		
Qualification: Plan	Test Results						
Reliability Test	Conditions	Conditions			Pass / Fail		
Reliability Test	Conditions		Lot :	1	Lot2	Lot 3	
**High Temp. Storage Bake	150C (500, 1000 F	lrs)	77/0)	77/0	77/0	
**Autoclave 121C	121C, 2 atm (96 H	rs)	77/0)	77/0	77/0	
**T/C -65C/150C	-65C/+150C (500	Cyc)	77/0)	77/0	77/0	
Manufacturability	(per mfg. Site spec	cification)	Pass	5	Pass	Pass	
Notes: **Preconditioning sec	quence: MSL2-260C						
Qual '	Vehicle 4: CDCVF25	05PW (MSL1-	260C)				
	Package Constru	ction Details					
Assembly Site:	MLA	Mold	Compoun	d:	4206193		
# Pins-Designator, Family:	8-PW, TSSOP	Mount	Compoun	d:	4042500		
Leadframe (Finish, Base):	NiPdAu, Cu		Bond Wir		0.96 Mil D	ia., Cu	
Qualification: Plan	☐ Test Results			,			
Reliability Test	Conditions				Pass / Fail		
Reliability Test		Lot	1	Lot2	Lot 3		
**High Temp. Storage Bake	150C (1000 Hrs)	77/0 77/0	_	77/0	77/0		
**Autoclave 121C	121C, 2 atm (96 Hr	121C, 2 atm (96 Hrs)			77/0	77/0	
**T/C -65C/150C	-65C/+150C (500 C	77/0)	77/0	77/0		
Manufacturability	(per mfg. Site speci	(per mfg. Site specification)			Pass	Pass	
Notes: **Preconditioning sequ	ience: MSL3-260C						

Qual Vehicle 5: DRV590GQC (MSL2A-235C)							
	Package Construction Details						
Assembly Site:	TAI	Mold Compound:					
# Pins-Designator, Family:	48-GQC, JRBGA	Mount Co	mpound:	4111062			
Solder Ball Composition:	SnPb	Во	nd Wire:	0.96 Mil Di	a., Cu		
Qualification: Plan Test Results							
Reliability Test	Y Test Conditions Pass / Fail						
Reliability Test			Lot 1	Lot2	Lot 3		
**High Temp. Storage Bake	150C (500, 1000 Hrs))	77/0	77/0	77/0		
**Autoclave 121C	121C, 2 atm (96 Hrs)		77/0	77/0	77/0		
*T/C -65C/150C	-65C/+150°C (500 Cycle	es)	77/0	77/0	77/0		
Manufacturability (per mfg. Site specification) Pass			Pass	Pass	Pass		
Notes: **Preconditioning sec	quence: MSL2A-235C						
Qual	Vehicle 6: F741900A	PFB (MSL3-250)C)				
	Package Construct	ion Details					
Assembly Site:	TAI	Mold Co	ompound:	4205442			
# Pins-Designator, Family:	48-PFB, TQFP	Mount Co	ompound:	4042504			
Leadframe (Finish, Base):	NiPdAu, Cu	В	ond Wire:	0.96 Mil D	ia., Cu		
Qualification:	Test Results						
Reliability Test	Conditions			Pass / Fail			
Reliability Test	Conditions		Lot 1	Lot2	Lot 3		
**High Temp. Storage Bake	150C (500, 1000 Hrs	5)	77/0	77/0	77/0		
**Autoclave 121C 121C, 2 atm (96 Hrs) 77/0 77/0			77/0				
**T/C -65C/150C				77/0			
				Pass			
Notes: **Preconditioning seq	uence: MSL3-250C						

Qual V	Qual Vehicle 7: SN75DP139RGZ (MSL3-260C)						
Package Construction Details							
Assembly Site: MLA Mold Compound							
# Pins-Designator, Family:	48-RGZ, VQFN	Mount Co	mpound:	4205846 0.96 Mil Dia Cu			
Leadframe (Finish, Base):	NiPdAu, Cu	Во	ond Wire:	0.96 Mil [Dia., Cu		
Qualification: Plan Test Results							
Reliability Test	Conditions			Pass / Fail Lot2 Lot 3			
Reliability Test	Conditions		Lot 1	Lot2	Lot 3		
**High Temp. Storage Bake	150C (500, 1000 Hrs))	77/0	77/0	77/0		
**Autoclave 121C	121C, 2 atm (96 Hrs)		77/0	77/0	77/0		
**T/C -65C/150C	-65C/+150C (500 Cyc	c)	77/0	77/0	77/0		
Manufacturability	(per mfg. Site specific	cation)	Pass	Pass	Pass		
Notes: **Preconditioning sequence: MSL3-260C							

Qual Vehic	le 8: SN75LVDS84	AADGG (M	SL2-2	60C))			
F	Package Construc	tion Detail	ls					
Assembly Site:	TAI	Мо	old Com	pound	l:	4209002		
# Pins-Designator, Family:	48-DGG, TSSOP	Mou	ınt Com	pound	l:	4042500		
Leadframe (Finish, Base):	NiPdAu, Cu		Bon	d Wire	e:	0.96 Mil Di	a., Cu	
Qualification: Plan X T	est Results				•			
Reliability Test	Conditions		Lo	ot 1	Pa	ss / Fail Lot2	Lot 3	
**High Temp. Storage Bake	150C (500, 1000	Hrs)		7/0		77/0	77/0	
**Autoclave 121C	121C, 2 atm (96 H		7	7/0		77/0	77/0	
**T/C -65C/150C	-65C/+150C (500	Cyc)	77	7/0		77/0	77/0	
Manufacturability	(per mfg. Site spe	cification)	Pa	ass		Pass	Pass	
Notes: **Preconditioning sequence	e: MSL2-260C							
Qual Vo	ehicle 9: THS7303	PW (MSL	2-260	C)				
F	Package Construc	tion Detail	ls					
Assembly Site:	TAI	Mold	Compo	und:	42	206193		
# Pins-Designator, Family:	20-PW, TSSOP	Mount	Compo	und:	40	142500	2500	
Leadframe (Finish, Base):	NiPdAu, Cu		Bond \	Wire:	0.	96 Mil Dia.,	, Cu	
Qualification:	Test Results							
Reliability Test	Conditions			Lat	1	Pass / Fail	Lat 2	
**High Temp. Storage Bake	150C (500, 100	n Hrs)		Lot 77/0		Lot2 77/0	Lot 3 77/0	
**Autoclave 121C	121C, 2 atm (90			77/0		77/0	77/0	
**T/C -65C/150C	-65C/+150C (50			77/0		77/0	77/0	
Bond Strength	76 ball bonds, 3			76/0		76/0	76/0	
Manufacturability	(per mfg. Site s		1)	Pass		Pass	Pass	
Notes: **Preconditioning sequence		•	,					
	hicle 10: THS7327	PHP (MSL	_3-260	OC)				
F	Package Construct	tion Detail	ls					
Assembly Site: Ta	ΔI	M	1old Co	mpoun	d:	4205443		
# Pins-Designator, Family: 48	8-PHP, HTQFP	Мо	unt Co	mpoun	d:	4042504		
	iPdAu, Cu		Во	nd Wir	e:	0.96 Mil Di	a., Cu	
Qualification:	Test Results							
Reliability Test	Conditions		_	l at :	1	Pass / Fail	Lot 2	
**High Temp. Storage Bake	150C (500, 1000 Hrs)			Lot :		Lot2 77/0	Lot 3 77/0	
**Autoclave 121C	121C, 2 atm			77/0		77/0	77/0	
**T/C -65C/150C	-65C/+150C			77/0		77/0	77/0	
Manufacturability	(per mfg. Site		ion)	Pass		Pass	Pass	
Notes: **Preconditioning seque		- specificat	,	. 45		. 200	. 2.55	

Qı	ıal V	/ehicle 11: TL16C5!	50DPTR (I	MSL1-26	(30C			
		Package Constru	iction Det	ails				
Assembly Site:	TAI		Mold	l Compour	nd:	42054	42	
# Pins-Designator, Family:	48-	PT, LQFP	Mount	Compour	nd:	4042504		
Leadframe (Finish, Base):	NiPo	dAu, Cu		Bond Wii	re: (0.96 N	1il Dia., C	u
Qualification:	n	☐ Test Results						
Reliability Test		Conditions				Pass ,	/ Fail	
Reliability Test		Conditions	onditions		1	L	ot2	Lot 3
**High Temp. Storage Ba	ike	150C (500, 1000 Hi	rs)	77/0)	7	7/0	77/0
**Autoclave 121C		121C, 2 atm (96 Hr	rs)	77/0)	7	7/0	77/0
**T/C -65C/150C		-65C/+150C (500 C	Cyc)	77/0)	7	7/0	77/0
Bond Strength		76 ball bonds, 3 uni	its min	76/0)	7	6/0	76/0
Manufacturability		(per mfg. Site specification) Pass Pass Pass			Pass			
Q	ual	Vehicle 12: TL16C7	'52BPT (MSL3-26	0C)			
		Package Constru	iction Det	ails				
Assembly Site	:: T	AI	Molo	d Compou	ınd:		42054	42
Pin Count, Package Family	/: 4	18-PT, LQFP	Moun	t Compou	ınd:		40425	04
Leadframe (Finish, Base): N	NiPdAu, Cu		Bond W	/ire:	0.96	Mil Dia	, Cu
Qualification:	n	☐ Test Results				!		
Dolinhility Tost		Conditions			Sar	nple S	Size (PAS	SS/FAIL)
Reliability Test		Conditions			Lot	#1	Lot#2	Lot#3
**High Temp. Storage Ba	ike	150C (500, 1	L000 Hours	s)	77	7/0	77/0	77/0
**Autoclave 121C		• • • • • • • • • • • • • • • • • • • •			77/0			
**T/C -65C/150C						77/0		
Manufacturability (Assembly		(per mfg. Site specification) Pass Pass Pass						
Notes: **Tests require pr								
N 1 44D 191 '	N-+ **P ##:: MCI 1 2000							

Notes: **Preconditioning sequence: MSL1-260C

Qual Vehicle 13: TLC5930PWP (MSL3-260C)								
Package Construction Details								
Assembly Site:	TAI	Mold Co	mpound:	4205443				
# Pins-Designator, Family:	24-PWP, HTSSOP	Mount Co	mpound:	4042504 0.96 Mil Dia., Cu				
Leadframe (Finish, Base):	NiPdAu, Cu	Во	nd Wire:	0.96 Mil Dia	ı., Cu			
Qualification: Plan Test Results								
Reliability Test	Conditions			Pass / Fail				
Reliability Test	Conditions		Lot 1	Lot2	Lot 3			
**High Temp. Storage Bake	150C (420 Hrs)		77/0	77/0	77/0			
**Autoclave 121C	121C, 2 atm (96 Hrs	5)	77/0	77/0	77/0			
**T/C -65C/150C	-65C/+150C (500, 1	77/0	77/0	77/0				
Manufacturability	(per mfg. Site specification) Pass Pass Pass				Pass			
Notes: **Tests require preco	nditioning sequence: I	MSL3-260C	Notes: **Tests require preconditioning sequence: MSL3-260C					

Qual \	/ehicle	14: TPA5050	RSA (MSL2-26	0C)			
Package Construction Details							
Assembly Site:	MLA		Mold Co	mpound:	4208625		
# Pins-Designator, Family:	16-RS/	A, VQFN	Mount Co	mpound:	4205846		
Leadframe (Finish, Base):	NiPdAu	ı, Cu	Во	ond Wire:	0.96 Mil I	Dia., Cu	
Qualification: Plan	Qualification: Plan Test Results						
Reliability Test		Conditions	Pass / Fail				
Reliability Test		Conditions		Lot 1	Lot2	Lot 3	
**High Temp. Storage Bake		150C (500, 1	000 Hrs)	77/0	77/0	77/0	
**Autoclave 121C		121C, 2 atm	(96 Hrs)	77/0	77/0	77/0	
**T/C -65C/150C		-65C/+150C	(500 Cyc)	77/0	77/0	77/0	
Bond Strength 76 ball bonds, min. 3 u		, min. 3 units	76/0	76/0	76/0		
Manufacturability (per mfg. Site specification) Pass Pass Pass					Pass		
Notes: **Preconditioning sequence: MSL2-260C							

Qual Vehicle 15: TPS5130PTR (MSL1-260C)							
	Package Construc	tion Details		_			
Assembly Site: TAI Mold Comp				4205442			
# Pins-Designator, Family:	ily: 48-PT, LQFP Mount Compound: 4042504						
Leadframe (Finish, Base):	NiPdAu, Cu	Во	ond Wire:	0.96 Mil I	Dia., Cu		
Qualification: Plan	Qualification: Plan Test Results						
Reliability Test	Conditions			Pass / Fail			
Reliability Test	Conditions		Lot 1	Lot2	Lot 3		
**High Temp. Storage Bake	150C (1000 Hrs)		77/0	77/0	77/0		
**Autoclave 121C	121C, 2 atm (96 Hrs)	1	77/0	77/0	77/0		
**T/C -65C/150C	-65C/+150C (500 Cy	c)	77/0	77/0	77/0		
Manufacturability	(per mfg. Site specification) Pass Pass Pass				Pass		
Notes: **Preconditioning sequence: MSL1-260C							

Qual \	Qual Vehicle 16: TPS51427ARHB (MSL2-260C)						
Package Construction Details							
Assembly Site:	Assembly Site: MLA Mold Compound: 4208625						
# Pins-Designator, Family:	32-RHB, VQFN	Mount Co	mpound:	4205846			
Leadframe (Finish, Base):	NiPdAu, Cu	Вс	nd Wire:	0.96 Mil E	Dia., Cu		
Qualification: Plan	Qualification: Plan Test Results						
Reliability Test	Conditions			Pass / Fai	<u> </u>		
Reliability Test	Conditions		Lot 1	Lot2	Lot 3		
**High Temp. Storage Bake	150C (500, 1000 Hrs))	77/0	77/0	77/0		
**Autoclave 121C	121C, 2 atm (96 Hrs)		77/0	77/0	77/0		
*T/C -65C/150C	-65C/+150°C (500 Cycle	es)	77/0	77/0	77/0		
Manufacturability	(per mfg. Site specific	cation)	Pass	Pass	Pass		
Notes: **Preconditioning sequence: MSL2-260C							

Qual Vehicle 17: TPS51620RHAR (MSL2-260C)							
Package Construction Details							
Assembly Site: MLA Mold Compound: 4208625							
# Pins-Designator, Family:	40-RHA, VQFN	Mount C	Compound:	4205	846		
Leadframe (Finish, Base):	NiPdAu, Cu	Į.	Bond Wire:	0.96	Mil Dia., C	Cu	
Qualification:	Test Results						
				Pass	/ Fail		
Reliability Test	Conditions		Lot 1		Lot2	Lot 3	
**High Temp. Storage Bake	150C (500, 1000 Hrs)		77/0		77/0	77/ 0	
**Autoclave 121C	121C, 2 atm (96 Hrs)		77/0		77/0	77/ 0	
**T/C -65C/150C	-65C/+150C (500 Cyc	2)	77/0		77/0	77/ 0	
Bond Strength	76 ball bonds, min. 3	units	76/0 76/0		76/ 0		
Manufacturability	(per mfg. Site specific	ation)	Pass Pass Pas			Pass	
Notes: **Preconditioning seq	uence: MSL2-260C						

Qual Vehicle 18: TPS77701PWP (MSL2-260C)							
Package Construction Details							
Assembly Site:	MLA	Mold Com	pound:	42054	143		
# Pins-Designator, Family:	48-RGZ, VQFN	Mount Com	pound:	40425	504		
Leadframe (Finish, Base):	NiPdAu, Cu	Bond	d Wire:	0.96 1	Mil Dia., Cı	۲	
Qualification: Plan Test Results							
Reliability Test	Conditions			Pass / Fail			
Reliability Test	Conditions		Lot 1		Lot2	Lot 3	
**High Temp. Storage Bake	150C (500, 1000 Hrs)	77	/0	77/0	77/0	
**Autoclave 121C	121C, 2 atm (96 Hrs))	77	/0	77/0	77/0	
**T/C -65C/150C	-65C/+150C (500 Cy	-65C/+150C (500 Cyc)			77/0	77/0	
Manufacturability (per mfg. Site specification) Pass Pass Pass					Pass		
Notes: **Preconditioning seque	ence: MSL2-260C		·		·		

Qual	Qual Vehicle 19: TPS77801PWP (MSL2-260C)						
Package Construction Details							
Assembly Site	e: TAI		Mold Compoun	d: 4209002	2		
# Pins-Designator, Famil	y: 20-PWP, HTSSOP		Mount Compoun	d: 4042500)		
Leadframe (Finish, Base): NiPdAu, Cu		Bond Wir	e: 0.96 Mi	l Dia., Cu		
Qualification:							
Reliability Test	Conditions			Pass / Fail			
Reliability Test	Conditions		Lot 1	Lot2	Lot 3		
**High Temp. Storage Bake	150C (500, 1000 Hrs)		77/0	77/0	77/0		
**Autoclave 121C	121C, 2 atm (96 Hrs)		77/0	77/0	77/0		
**T/C -65C/150C	-65C/+150C (500 Cyc	55C/+150C (500 Cyc)			77/0		
Manufacturability	nufacturability (per mfg. Site specification) Pass Pass Pass				Pass		
Notes: **Preconditioning sequ	uence: MSL2-260C	·	·				

Qual Veh	icle 20: TSB12LV21B	PGF (MSI	.3-260C)			
Package Construction Details						
Assembly Site: PHI Mold Compound: 4205442						
# Pins-Designator, Family	: 176-PGF, LQFP	Mou	nt Compound	: 404250)4	
Leadframe (Finish, Base)	: NiPdAu, Cu		Bond Wire	: 0.96 M	il Dia., Cu	
Qualification: Plan Test Results						
Reliability Test	Conditions		Pass / Fail			
Reliability Test	Conditions		Lot 1	Lot2	Lot 3	
**High Temp. Storage Bake	150C (500, 1000 Hrs)		77/0	77/0	77/0	
**Autoclave 121C	121C, 2 atm (96 Hrs)		77/0	77/0	77/0	
**T/C -65C/150C	-65C/+150C (500 Cyc	:)	77/0	77/0	77/0	
Bond Strength	76 ball bonds, 3 units min 76/0 76/0			76/0		
Manufacturability (per mfg. Site specification) Pass Pass Pass					Pass	
Notes: **Preconditioning sequence: MSL3-260C						

Qual Vehicle 21: TSB41AB1PHP (MSL3-260C)									
Package Construction Details									
Assembly Site:	TAI	Mold Compo	und:	42	05443				
# Pins-Designator, Family:	48-PHP, HTQFP	Mount Compo	und:	40	42504				
Leadframe (Finish, Base):	NiPdAu, Cu	Bond	Wire:	0.9	96 Mil Dia.,	Cu			
Qualification: Plan Test Results									
Reliability Test	Conditions	Conditions			Pass / Fail				
Reliability Test	Conditions		Lot	1	Lot2	Lot 3			
**High Temp. Storage Bake	150C (500, 1000 H	lrs)	77/	0	77/0	77/0			
**Autoclave 121C	121C, 2 atm (96 H	rs)	77/0		77/0	77/0			
*T/C -65C/150C	-65C/+150°C (500	-65C/+150°C (500 Cycles)			77/0	77/0			
Manufacturability	(per mfg. Site specification) Pass Pass Pa				Pass				
Notes: **Preconditioning sequence: MSL3-260C									

Qual Vehicle 22: TSB81BA3EPFP (MSL3-260C)								
Package Construction Details								
Assembly Site:	TAI	Mold Cor	mpound:	4205443				
# Pins-Designator, Family:	80-PFP, TQFP	Mount Cor	mpound:	4042504				
Leadframe (Finish, Base):	NiPdAu, Cu	В	ond Wire:	0.8 Mil Dia., Cu				
Qualification: Plan Test Results								
Reliability Test	Conditions			Pass / Fail				
Reliability Test	Conditions		Lot 1	Lot2	Lot 3			
**High Temp. Storage Bake	150C (500, 1000 H	rs)	77/0	77/0	77/0			
**Autoclave 121C	121C, 2 atm (96 H	rs)	77/0	77/0	77/0			
**T/C -65C/150C	-65C/+150C (500 Cyc) 77/0 77/0				77/0			
Bond Strength	76 ball bonds, min.	76/0	76/0	76/0				
Manufacturability	(per mfg. Site specification) Pass Pass				Pass			
Notes: **Preconditioning sequence: MSL3-260C								

Qual Vehicle 23: TVAIC3106IZQER (MSL3-260C)								
Package Construction Details								
Assembly Site:	PHI	Mold Cor	mpound:	4205867				
# Pins-Designator, Family:	80-ZQE, BGA	Mount Cor	mpound:	4111062				
Solder Ball Composition:	SnAgCu	Во	nd Wire:	0.8 Mil D	ia., Cu			
Qualification: Plan Test Results								
Reliability Test	Conditions			Pass / Fail				
Reliability Test	Conditions		Lot 1	Lot2	Lot 3			
**High Temp. Storage Bake	150C (500, 1000 H	rs)	77/0	77/0	77/0			
**Autoclave 121C	121C, 2 atm (96 H	rs)	77/0	77/0	77/0			
**T/C -65C/150C	-65C/+150C (500 Cyc) 77/0 77/0				77/0			
Bond Strength	76 ball bonds, min. 3 units 7			76/0	76/0			
Manufacturability	(per mfg. Site specification) Pass Pass Pass				Pass			
Notes: **Preconditioning sequence: MSL3-260C								

Qual Vehicle 24: UCC5696PN (MSL3-260C)									
Package Construction Details									
Assembly Site:	TAI	Mold Compo	und:	420544	-2				
# Pins-Designator, Family:	80-PN,LQFP	Mount Compo	und:	404250	4				
Leadframe (Finish, Base):	NiPdAu, Cu	Bond	d Wire: 0.96 Mil Dia., C			, Cu			
Qualification:									
Reliability Test	Conditions			Pass	/ Fail				
Kellability Test	Conditions		Lot	1 Lo	ot2	Lot 3			
**High Temp. Storage Bake	150C (500, 1000 F	łrs)	77/0) 77	' /0	77/0			
**Autoclave 121C	121C, 2 atm (96 H	121C, 2 atm (96 Hrs) 77/0				77/0			
*T/C -65C/150C	-65C/+150°C (500	-65C/+150°C (500 Cycles) 77/0 77/0				77/0			
Manufacturability	(per mfg. Site specification) Pass Pass Pass					Pass			
Notes: **Preconditioning sequence: MSL3-260C									

Qual Vehicle 25: VSP6825AZRCR (MSL3-260C)									
Package Construction Details									
Assembly Site:	TAI	Mold Cor	mpound:	4205867					
# Pins-Designator, Family:	103-ZRC, JrBGA	Mount Cor	mpound:	4111062					
Solder Ball Composition:	SnAgCu	Во	nd Wire:	0.8 Mil D	ia., Cu				
Qualification: Plan Test Results									
Reliability Test	Conditions			Pass / Fail					
Reliability Test	Conditions		Lot 1	Lot2	Lot 3				
**High Temp. Storage Bake	150C (500, 1000 F	lrs)	77/0	77/0	77/0				
**Autoclave 121C	121C, 2 atm (96 H	rs)	77/0	77/0	77/0				
**T/C -65C/150C	-65C/+150C (500	Cyc)	77/0	77/0	77/0				
Bond Strength	76 ball bonds, min	76/0	76/0	76/0					
Manufacturability	(per mfg. Site specification) Pass Pass Pass				Pass				
Notes: **Preconditioning sequence: MSL3-260C									

Qualification Data: Approved 07/01/2011

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.									
Qual	Qual Vehicle 1 : DRV401AIRGW (MSL 2-260C)								
Package Construction Details									
Assembly Site:	Clarl	k AT	Mold Compo	ound:	4208625	,			
# Pins-Designator, Family:	20-F	RGW,VQFN	Mount Compo	ound:	4207768	3			
Leadframe (Finish, Base):	NiPd	lAu, Cu	Bond	Wire:	0.96 Mil	Dia., Cu			
Qualification: Plan Test Results									
Reliability Test		Conditions		Pass /		/ Fail			
Reliability Test		Conditions		Lot 1	Lot2	Lot 3			
**High Temp. Storage Bake		170C (420 Hrs)		77/0	77/0	77/0			
**Autoclave 121C		121C, 2 atm (96 I	Hrs)	77/0	77/0	77/0			
**T/C -65C/150C		-65C/+150C (500	Cyc)	77/0	77/0	77/0			
Ball Bond Shear		76 balls 3 units m	nin	76/0	76/0	76/0			
Bond Pull		76 Wire 3 units min		76/0	76/0	76/0			
Manufacturability		(per mfg. Site spe	ecification)	Pass	Pass	Pass			
X-ray		(top side only)		5/0	5/0	5/0			
Notes: **Preconditioning sequence: MSL2-260C									

Oual Vel	nicle 2	2 : SN75DP1	L 22	ARTQ (MSL3-	260	C)		
		age Constri						
Assembly Site:	Clar	k-AT		Mold Comp	oun	d:	4208625	
# Pins-Designator, Family:	56-RTQ, VQFN Mount Comp					4207768		
Leadframe (Finish, Base):				Bond	l Wir	e:	0.96 Mil Dia	., Cu
		Results				1		•
Reliability Test		Conditions					Pass / Fai	
·						ot 1	Lot2	Lot 3
**High Temp. Storage Bake		170C (420			-	7/0	77/0	77/0
**Autoclave 121C		121C, 2 atr			-	7/0	77/0	77/0
**T/C -65C/150C		-65C/+150				7/0		77/0
Ball Bond Shear		76 balls 3 ι				6/0	76/0	76/0
Bond Pull		76 Wire 3 u			-	6/0	76/0	76/0
Manufacturability				specification)		ass	Pass	Pass
X-ray		(top side or	ıly)		,	5/0	5/0	5/0
Notes: **Preconditioning seque				NIDD (146: 5 5				
Quai ve				RHBR (MSL2-2	2600	<i>-</i>)		
A so simple City		age Constru	ucu		. اد	420	20625	
Assembly Site:	Clark		Η.	Mold Compour			08625	
# Pins-Designator, Family:	32-RHB, VQFN Mount Compou							
				re:	0.8	Mil Dia., Cu		
Qualification: Plan Test Results								
Reliability Test	Conditions			1 0	ot 1	Pass / Fail Lot2	Lot 3	
**High Temp. Storage Bake	170C (1000 Hrs)				77/0		77/0	77/0
**Biased HAST	130C/85%RH (96 Hrs))		7/0	77/0	77/0
**Autoclave 121C		, 2 atm (96 H				7/0	77/0	77/0
**T/C -55C/125C		+125C (1000		/c)	7	7/0	77/0	77/0
*T/C -65C/150C		+150°C (500			7	7/0	77/0	77/0
Manufacturability		nfg. Site spe			P	ass	Pass	Pass
Moisture Sensitivity	(level	3 @ 260C +	5/-0	0C)	17	2/0	12/0	12/0
Notes: **Preconditioning sequ	ence:	MSL2-260C						
Qual Ve	hicle	4 : TPA2005	5D1	DRB (MSL 2-2	2600	2)		
		age Constru	ucti	on Details				
Assembly S	Site:	Clark-AT		Mold Comp		-	4208625	
# Pins-Designator, Fan	nily:	8-DRB, VSO	N	Mount Comp	oun	d:	4207768	
Leadframe (Finish, Ba		NiPdAu, Cu		Bond	l Wir	e:	0.96 Mil Dia	., Cu
Qualification: Plan	Test	Results					D / = -	1
Reliability Test	Conditions			Lo	t 1	Pass / Fai Lot2	Lot 3	
**High Temp. Storage Bake	170C (420	Hrs)	+	7/0	77/0	77/0	
**Autoclave 121C	121C, 2 atr	n (9	96 Hrs)	7	7/0	77/0	77/0	
			C (5	500 Cyc)	7	7/0	77/0	77/0
Ball Bond Shear 76 balls			ınits	s min	76	6/0	76/0	76/0
Bond Pull		76 Wire 3 ເ	ınits	s min	76	5/0	76/0	76/0
Manufacturability		(per mfg. S	(per mfg. Site specification)		_	ass	Pass	Pass
X-ray		(top side or	nly)		5	/0	5/0	5/0
Notes: **Preconditioning sequen	ice: Le	evel 3-260C						

Qual Vehicle 5: TPS51217DSCR_RFAB (MSL2-260C)						
Package Construction Details						
Assembly Site:	Clark-	-AT	Mold C	ompound:	4208625	
# Pins-Designator, Family:	10-DS	SC, WSON	Mount C	ompound:	4207768	
Leadframe (Finish, Base):	NiPdA	u, Cu	В	ond Wire:	0.96 Mil [Dia., Cu
Qualification:	Test F	Results				
Reliability Test		Conditions				
Reliability Test		Conditions		Lot 1	Lot2	Lot 3
High Temp Operating Life (Analo	perating Life (Analog) 125C (1000		rs), Vddmax	77/0	77/0	77/0
		170C (420 Hrs)		77/0	77/0	77/0
**Biased HAST		130C/85%RH	(96 Hrs)	77/0	77/0	77/0
**Autoclave 121C		121C, 2 atm (96 Hrs)	77/0	77/0	77/0
**T/C -65C/150C		-65C/+150C (500 Cyc)		77/0	77/0	77/0
Ball Bond Shear		76 balls 3 units min		76/0	76/0	76/0
Bond Pull		76 Wire 3 units min		76/0	76/0	76/0
Manufacturability		(per mfg. Site	specification)	Pass	Pass	Pass
X-ray (top sid		(top side only)		5/0	5/0	5/0
Notes: **Preconditioning sequence: Level 2-260C						
Qual Vehicle 6 : TPS51217DSC_UMC (MSL2-260C)						
Package Construction Details						

Qual Vehicle 6 : TPS51217DSC_UMC (MSL2-260C)							
Package Construction Details							
Assembly Site:	Clark-AT	Mold Com	oound:	4208625			
# Pins-Designator, Family:	10-DSC, WSON	Mount Com	oound:	4207768			
Leadframe (Finish, Base):	NiPdAu, Cu	Bond	d Wire:	0.96 Mil Dia	a., Cu		
Qualification: Plan Test Results							
Deliability Test	Conditions			Pass / Fai	I		
Reliability Test	Conditions	Conditions			Lot 3		
**High Temp. Storage Bake	170C (420 Hrs)		77/0	77/0	77/0		
**Autoclave 121C	121C, 2 atm (96 Hr	s)	77/0	77/0	77/0		
**T/C -65C/150C	-65C/+150C (500 C	Cyc)	77/0	77/0	77/0		
Ball Bond Shear	76 balls 3 units min		76/0	76/0	76/0		
Bond Pull	76 Wire 3 units min	76 Wire 3 units min 76/0 76					
Manufacturability	(per mfg. Site specification) Pass Pass Pass				Pass		
X-ray	(top side only) 5/0 5/0 5/0				5/0		
Notes: **Preconditioning sequence: MSL2-260C							

Qual Vehicle 7: TPS51621RHA (MSL3-260C)						
Package Construction Details						
Assembly Site:	Clark-AT	Mold Com	pound:	42086	25	
# Pins-Designator, Family:	40-RHA, VQFN	Mount Com	pound:	42077	68	
Leadframe (Finish, Base):	NiPdAu, Cu	Bond	d Wire:	0.96 N	1il Dia., Cu	
Qualification: Plan T	est Results					
Reliability Test	Conditions	Conditions		Pass	/ Fail	
Reliability Test	Conditions			Lot2	Lot 3	
**High Temp. Storage Bake	170C (420 Hrs	170C (420 Hrs)		77/0	77/0	
**Autoclave 121C	121C, 2 atm (9	121C, 2 atm (96 Hrs)		77/0	77/0	
**T/C -65C/150C	-65C/+150C (5	-65C/+150C (500 Cyc)		77/0	77/0	
Ball Bond Shear	76 balls 3 units	76 balls 3 units min		76/0	76/0	
Bond Pull	76 Wire 3 units	76 Wire 3 units min		76/0	76/0	
Manufacturability	(per mfg. Site	specification)	Pass	Pass	Pass	
X-ray (top side only) 5/0 5/0 5/0			5/0			
Notes: **Preconditioning sequence: MSL3-260C						

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com